TRADEMARK ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE BY SECURED PARTY

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
Hercules Technology II, L.P.		102/10/2009	LIMITED PARTNERSHIP: DELAWARE

RECEIVING PARTY DATA

Name:	Enpirion, Inc.		
Street Address:	685 Route 2020/206		
City:	Bridgewater		
State/Country:	NEW JERSEY		
Postal Code:	08807		
Entity Type:	CORPORATION: DELAWARE		

PROPERTY NUMBERS Total: 2

Property Type Number		Word Mark
Serial Number:	78314915	ENPIRION
Serial Number: 78315036		

CORRESPONDENCE DATA

Fax Number: (866)369-2815

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 847-542-1858

Email: ebagarella@herculestech.com

Correspondent Name: Eileen M. Bagarella Address Line 1: 934 Church Street

Address Line 4: Elmhurst, ILLINOIS 94301

NAME OF SUBMITTER:	Eileen M. Bagarella
Signature:	/s/Eileen M. Bagarella
Date:	02/20/2009

TRADEMARK REEL: 003939 FRAME: 0423

900127552

Total Attachments: 6

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TERMINATION OF

PATENT SECURITY AGREEMENT

This Termination of the Intellectual Property Security Agreement (the "Termination"), dated as of February 10, 2009, is executed by Hercules Technology II, L.P., a Delaware limited partnership ("Secured Party") in favor of Enpirion, Inc., a Delaware corporation (the "Debtor").

RECITALS

WHEREAS, the Debtor and the Secured Party entered into a certain Loan and Security Agreement dated as of May 23, 2008 (the "Loan Agreement"); and

WHEREAS, in connection with Loan Agreement, the Debtor entered into a certain Intellectual Property Security Agreement dated as of May 23, 2008 (the "Assignment"); and

WHEREAS, pursuant to the Assignment, the Company granted to the Secured Party a security interest in certain Collateral (as defined in the Assignment) including certain intellectual property; and

WHEREAS, the Collateral in the Loan Agreement has been released, including all of the intellectual property described in the Assignment. Accordingly, the Assignment is terminated.

NOW, THEREFORE, the Secured Party agrees as follows:

- 1. The Secured Party is executing and delivering this Termination as evidence of the termination of the Assignment.
- 2. The Secured Party claims no right title or interest whatsoever in or to any of the Collateral described in the Assignment and the Secured Party expressly terminates its security interest in the intellectual property listed on Exhibit A hereto, which security interest was evidenced by the recordation of the Assignment with the United States Patent and Trademark Office.

IN WITNESS WHEREOF, this Termination is executed as of the first date written above.

HERCULES TECHNOLOGY II, L.P., a Delaware limited partnership

By: Hercules Technology SBIC Management,

LLC, its General Partner

By: Hercules Technology Growth Capital, Inc.,

its Manager

By: Name: K. Nicholas Martitsch

Its: Associate General Counsel

Exhibit A

Patents

- 18 US Patents Issued to Eppirion as of April 10, 2008.
- 1 7,335,948 Integrated circuit incorporating higher voltage devices and low voltage devices therein
- 2 7,330,017 Driver for a power converter and a method of driving a switch thereof
- 3 7,276,998 Encapsulated package for a magnetic device
- 4 7,256,674 Power module
- 5 7,244,994 Laterally diffused metal oxide semiconductor device and method of forming the same
- 6 7,232,733 Method of forming an integrated circuit incorporating higher voltage devices and low voltage devices therein
- 7 7.230,302 Laterally diffused metal oxide semiconductor device and method of forming the same
- 8 7.229,886 Method of forming an integrated circuit incorporating higher voltage devices and low voltage devices therein
- 9 7,214,985 Integrated circuit incorporating higher voltage devices and low voltage devices therein
- 10 7,195,981 Method of forming an integrated circuit employable with a power converter
- 11 7,190,026 Integrated circuit employable with a power converter
- 12 7,186,606 Method of forming an integrated circuit employable with a power converter
- 13 7,180,395 Encapsulated package for a magnetic device
- 14 7,144,489 Photochemical reduction of Fe(III) for electroless or electrodeposition of iron alloys
- 15 7,122,105 Use of siderophores to increase the current efficiency of iron plating solutions
- 16 7,038,438 Controller for a power converter and a method of controlling a switch thereof
- 17 7,019,505 Digital controller for a power converter employing selectable phases of a clock signal
- 18 7,015,544 Intergrated circuit employable with a power converter
- 19 Patent Applications Pending with USPTO

ENP	16	10/985,825	Method of Manufacturing an Encapsulated Package for a Magnetic Device	Pending 11/10/04
ENP	17	10/985,150	Method of Manufacturing a Power Module	Pending 11/10/04

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ENI	PI	8 17/244.13	27 Magnetic Device Having a Conductive Clip	Pending 10/5/05
ENI	9 1	9 11/243,53	Method of Forming a Magnetic Device Havin a Conductive Clip	Pending 10/5/05
ENF	2 20		Having a Conductive Clip	Pending 10/5/05
ENF	21	11/243,78	7 Method of Forming a Power Module With a Magnetic Device Having a Conductive Clip	Pending 10/5/05
ENP	22	11/368,55	9 Controller for a Power Converter and Method of Operating the Same	Pending 3/6/06
ENP			Gate Drive Circuit	Pending 7/20/06
ENP	24	11/584,721	Controller Including Sawtooth Generator and Method of Operating the Same	Pending 10/20/06
ENP	25	11/852,688	MICROMAGNETIC DEVICE AND METHOD OF FORMING THE SAME	Pending 9/10/07
ENP	26	11/852,689	METHOD OF FORMING A MICROMAGNETIC DEVICE	Pending 9/10/07
ENP	27	11/852,692	POWER CONVERTER EMPLOYING A MICROMAGNETIC DEVICE	Pending 9/10/07
ENP	28	11/852,697	MICROMAGNETIC DEVICE AND METHOD OF FORMING THE SAME	Pending 9/10/07
ENP	29	11/852,698	METHOD OF FORMING A MICROMAGNETIC DEVICE	Pending 9/10/07
NP	30	11/852,703	POWER CONVERTER EMPLOYING A MICROMAGNETIC DEVICE	Pending 9/10/07
NP	31	11/852,707	ELECTROPLATING CELL AND TOOL	Pending 9/10/07
NP	32	11/852,710	ELECTROLYTE AND METHOD OF PRODUCING THE SAME	Pending 9/10/07
		11/852,716	METHODS OF PROCESSING A SUBSTRATE AND FORMING A MICROMAGNETIC DEVICE	Pending 9/10/07
NP 3	34	11/965,618	On for Pre-Charged Output Capacitor	Pending, Filed 12/17/2007

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Trademarks

Application No.	<u>Mark</u>	Final Status
78314915 78315036	ENPIRION Enpirion design	Registered 8-02-05; Reg. No. 2,982,007 Registered 8-30-05; Reg. No. 2,990,452

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Licenses

LICENSED PATENTS

1. Patent and Technology License Agreement, dated as of August 27, 2002, between Agere Systems Guardian Corporation, Agere Systems and Enpirion, as amended by Letter Agreement dated June 1, 2004. Below is a list of all IP licensed under such Agreement. Agere Systems is now LSI Corp.

U.S. PATENTS LICENSED FROM AGERE SYSTEMS, INC.:

U.S. Patent No.	<u>Title</u>
6,369,408	GaAs MOSFET Having Low Capacitance and On-Resistance
6,495,019	Device Comprising Micromagnetic Components for Power Applications
6,118,351	Micromagnetic Device for Power Processing Applications
6,160,721	Micromagnetic Device for Power Processing Applications
6,163,234	Micromagnetic Device for Data Transmission Applications
6,191,495	Micromagnetic Device Having an Anisotropic Core
6,255,714	Integrated Circuit Having a Micromagnetic Device Including a
	- Ferromagnetic Core
6,005,377	Programmable Digital Controller for Switched Mode Power Conversion
	and Power Supply Employing the Same
6.038,163	Capacitor Loaded Memory Cell
6,272,039	Temperature Insensitive Capacitor Loaded Memory Cell
6,285,166	Battery Charger with Improved Overcharge Protection Mechanism and
	Method of Operation Thereof
6,285,223	Power Up Circuit for Analog Circuits
6,351,033	Multifunction Lead Frame and Integrated Circuit Package
6,573,818	Planar Magnetic Frame Inductors having Open Cores
6,541,819	A Semiconductor Device Having Non-Power Enhanced and Power
	Enhanced Metal Oxide Semiconductor Devices

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6,440,750	Method of Making Integrated Circuit having a Micromagnetic Device
6,682,962	GaAs MOSFET Having Low Capacitance and On-Resistance
6,903,373	SiC NMOSFET For Use As a Power Switch
7,021,518	Micromagnetic Device for Power Processing Applications**

** 09/484498 Abandoned by Agere; 7,021,518 issued as CIP on April 04, 2006. Application 387846 is a continuation of currently pending application Ser. No. 09/484,498, filed Jan. 18, 2000, Abandoned by Kossives, et al., and entitled "A Micromagnetic Device for Power Processing Applications And Method of Manufacture Therefor." The application Ser. No. 09/484,498 is a divisional of application Ser. No. 08/872,250, filed Jun. 10, 1997, which issued on Sep. 12, 2000, as U.S. Pat. No. 6,118,351 to Kossives, et al., and entitled "Micromagnetic Device for Power Processing Applications And Method of Manufacture Therefor." The abovelisted application, Ser. No. 09/484,498 and U.S. Pat. No. 6,118,351, are commonly assigned with the present invention and are incorporated herein by reference

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RECORDED: 02/20/2009